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BDW73, BDW73A, BDW73B, BDW73C, BDW73D NPN SILICON POWER DARLINGTONS

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AUGUST 1978 - REVISED MARCH 1997

- Designed for Complementary Use with BDW74, BDW74A, BDW74B, BDW74C and BDW74D
- 80 W at 25°C Case Temperature
- 8 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 3 A

TO-220 PACKAGE (TOP VIEW) B 1 2 B 3

Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	BDW73		45	Ŋ.
	BDW73A	111	60	34
Collector-base voltage (I _E = 0)	BDW73B	V _{CBO}	80	V
	BDW73C	WWW.	100	
90.	BDW73D		120	
- RA 16/10	BDW73		45	
	BDW73A		60	
Collector-emitter voltage (I _B = 0) (see Note 1)	BDW73B	V_{CEO}	80	V
Collector-emitter voltage (I _B = 0) (see Note 1)	BDW73C		100	
MMM	BDW73D		120	
Emitter-base voltage	V _{EBO}	5	V	
Continuous collector current	I _C	8	Α	
Continuous base current	I _B	0.3	Α	
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)	P _{tot}	80	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3	P _{tot}	2	W	
Unclamped inductive load energy (see Note 4)	½LI _C ²	75	mJ	
Operating junction temperature range	Tj	-65 to +150	°C	
Operating temperature range	T _{stg}	-65 to +150	°C	
Operating free-air temperature range	T _A	-65 to +150	°C	

- NOTES: 1. These values apply when the base-emitter diode is open circuited.
 - 2. Derate linearly to 150°C case temperature at the rate of 0.64 W/°C.
 - 3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.
 - 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, $I_{B(on)}$ = 5 mA, R_{BE} = 100 Ω , $V_{BE(off)}$ = 0, R_{S} = 0.1 Ω , V_{CC} = 20 V.

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electrical characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER		TEST	CONDITIONS		MIN	TYP	MAX	UNIT
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = 30 mA	I _B = 0	(see Note 5)	BDW73 BDW73A BDW73B BDW73C BDW73D	45 60 80 100 120			V
I _{CEO}	Collector-emitter cut-off current	$V_{CE} = 40 \text{ V}$ $V_{CE} = 50 \text{ V}$	$I_{B} = 0$		BDW73 BDW73A BDW73B BDW73C BDW73D	120		0.5 0.5 0.5 0.5 0.5	mA
Ісво	Collector cut-off current	$V_{CB} = 80 \text{ V}$ $V_{CB} = 100 \text{ V}$ $V_{CB} = 120 \text{ V}$ $V_{CB} = 45 \text{ V}$ $V_{CB} = 60 \text{ V}$ $V_{CB} = 80 \text{ V}$ $V_{CB} = 100 \text{ V}$	E = 0 E = 0	$T_{C} = 150^{\circ}\text{C}$	BDW73 BDW73A BDW73B BDW73C BDW73D BDW73 BDW73A BDW73A BDW73B BDW73C BDW73D			0.2 0.2 0.2 0.2 0.2 5 5 5 5	mA
I _{EBO}	Emitter cut-off current		I _C = 0					2	mA
h _{FE}	Forward current transfer ratio	$V_{CE} = 3 V$ $V_{CE} = 3 V$	$I_C = 3 A$ $I_C = 8 A$	(see Notes 5 and 6)		750 100		20000	
V _{BE(on)}	Base-emitter voltage	V _{CE} = 3 V	I _C = 3 A	(see Notes 5 and 6)				2.5	V
V _{CE(sat)}	Collector-emitter saturation voltage	$I_B = 12 \text{ mA}$ $I_B = 80 \text{ mA}$	$I_C = 3 A$ $I_C = 8 A$	(see Notes 5 and 6)				2.5 4	V
V _{EC}	Parallel diode forward voltage	I _E = 8 A	I _B = 0					3.5	٧

NOTES: 5. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.56	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS †				TYP	MAX	UNIT
t _{on}	Turn-on time	I _C = 3 A	$I_{B(on)} = 12 \text{ mA}$	$I_{B(off)} = -12 \text{ mA}$		1		μs
t _{off}	Turn-off time	$V_{BE(off)} = -3.5 \text{ V}$	$R_L = 10 \Omega$	$t_p = 20 \ \mu s, \ dc \le 2\%$		5		μs

[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

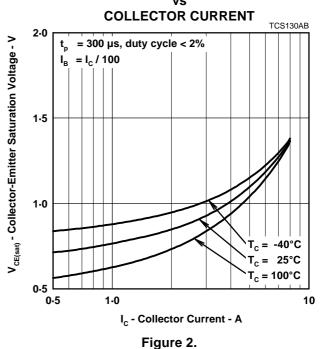
^{6.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

TYPICAL CHARACTERISTICS

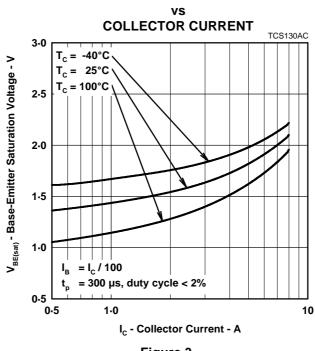
TYPICAL DC CURRENT GAIN COLLECTOR CURRENT TCS130AD 50000 $T_c = -40^{\circ}C$ $T_c = 25^{\circ}C$ $T_{\rm C} = 100^{\circ}{\rm C}$ h_{FE} - Typical DC Current Gain 10000 1000 3 V = 300 μs, duty cycle < 2% 100 0.5 10 I_c - Collector Current - A

Figure 1.

COLLECTOR-EMITTER SATURATION VOLTAGE



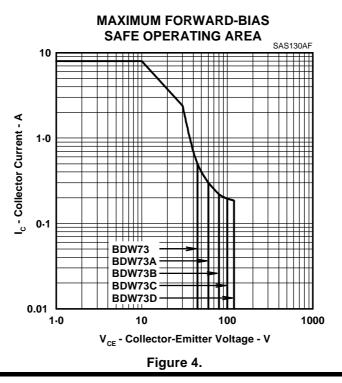
BASE-EMITTER SATURATION VOLTAGE







MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION

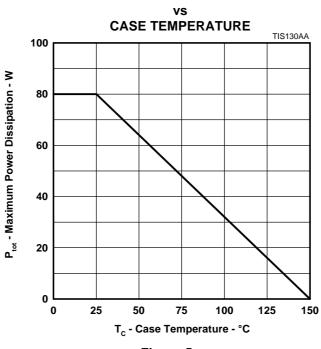


Figure 5.

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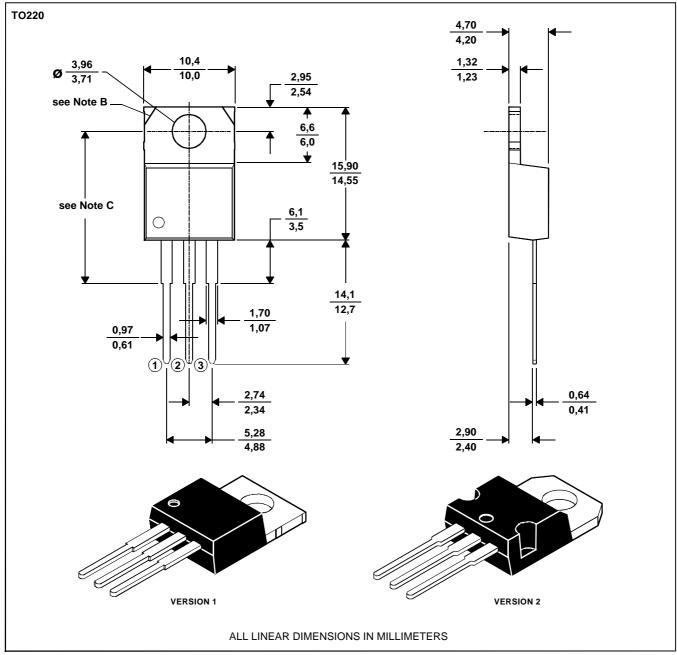
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

- B. Mounting tab corner profile according to package version.
- C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm.

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AUGUST 1978 - REVISED MARCH 1997

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